

GENERAL DESCRIPTION

The SGM62117 is a synchronous 4-switch Buck-Boost converter which is suitable for battery operated applications. The device's programmable light load PFM mode and low quiescent current (18µA, TYP) offer above 90% efficiency in the 10mA to 2A output current range. The output voltage is programmable via external feedback resistor divider.

The SGM62117 can operate in Buck, Boost or a novel 4-cycle Buck-Boost mode when the input voltage is close to or equal to the output voltage. The device implements pre-defined mode transition thresholds to avoid undesired toggling within modes to reduce output voltage ripple.

The SGM62117 offers various protection features to improve device robustness such as over-temperature, input over-voltage and output over-current protections. These features can protect the device against unexpected system failure.

The SGM62117 is available in a small Green TDFN-3×2-10L package. High integration provides a compact solution with only six external components.

TYPICAL APPLICATION

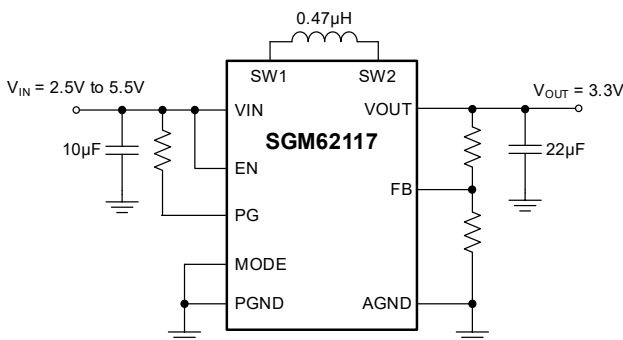


Figure 1. Typical Application Circuit

FEATURES

- 2.2V to 5.5V Input Voltage Range
- 1.8V to 5.2V Output Voltage Range (Adjustable)
- 2A Output Current for $V_{IN} \geq 2.5V$ and $V_{OUT} = 3.3V$
- Above 90% Efficiency for I_{OUT} from 10mA to 2A
- High Efficiency over the Entire Load Range
- 18µA (TYP) Quiescent Current
- Programmable Forced PWM Mode and Pulse Frequency Modulation Mode
- Real Buck, Boost and Buck-Boost Modes
- Power Good
- Internal Soft-Start
- Start-up into Pre-Biased Outputs
- Forward and Reverse Current Operation and Current Limit
- OTP, Input OVP and Output OCP Protections
- True Shutdown Function with Load Disconnect
- Available in a Green TDFN-3×2-10L Package

APPLICATIONS

- System Pre-Regulator
- Point-of-Load Regulation
- Thermoelectric Devices
- Battery Backup
- Voltage Stabilizer and Converter

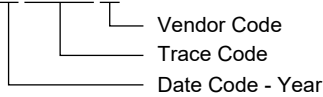
PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGM62117	TDFN-3x2-10L	-40°C to +125°C	SGM62117XTGH10G/TR	01KGH XXXXX	Tape and Reel, 3000

MARKING INFORMATION

NOTE: XXXXX = Date Code, Trace Code and Vendor Code.

XXXXX



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS

- Input Voltages
- VIN, SW1, SW2, EN, MODE, VOUT, FB, PG -0.3V to 6V
- SW1, SW2 (AC, less than 10ns) Voltages..... -0.3V to 8V
- Package Thermal Resistance
- TDFN-3x2-10L, θ_{JA} 76°C/W
- Junction Temperature +150°C
- Storage Temperature Range -65°C to +150°C
- Lead Temperature (Soldering, 10s) +260°C
- ESD Susceptibility
- HBM 3000V
- CDM 1000V

RECOMMENDED OPERATING CONDITIONS

- Input Voltage, VIN 2.2V⁽¹⁾ to 5.5V
- Output Voltage, VOUT 1.8V to 5.2V⁽²⁾
- Effective Capacitance Connected to VIN, CIN 4µF (MIN), 5µF (TYP)
- Effective Inductance, L 0.37µH to 0.57µH, 0.47µH (TYP)
- Effective Capacitance Connected to VOUT, COUT
- 1.8V ≤ VOUT ≤ 2.3V 10µF (MIN)
- VOUT > 2.3V 7µF (MIN), 8.2µF (TYP)
- Operating Junction Temperature, TJ -40°C to +125°C

OVERSTRESS CAUTION

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

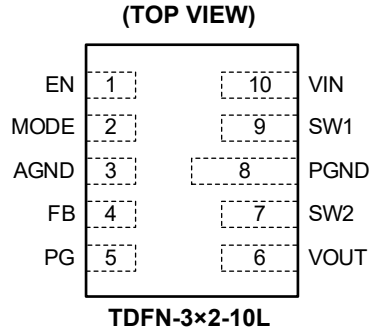
ESD SENSITIVITY CAUTION

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

PIN CONFIGURATION



PIN DESCRIPTION

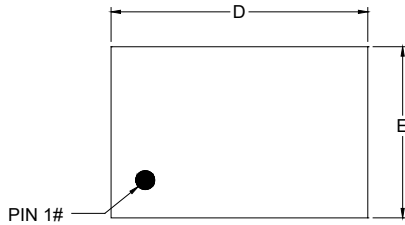
PIN	NAME	TYPE	DESCRIPTION
1	EN	I	Active High Logic. Device Enable Input. Do not leave it floating.
2	MODE	I	Logic 0 for PFM Mode and Logic 1 for Forced PWM Mode. Do not leave it floating.
3	AGND	G	Analog Ground. Connect it to the PGND pin under the chip.
4	FB	I	Voltage Feedback Pin. Connect a resistor divider at FB pin to program the output voltage.
5	PG	O	Power Good Indicator. Open-Drain Output. Leave it floating if not used.
6	VOUT	O	Converter Output.
7	SW2	P	Boost Leg Connection for Inductor.
8	PGND	G	Power Ground.
9	SW1	P	Buck Leg Connection for Inductor.
10	VIN	I	Supply Voltage for Power Stage and Control Stage.

NOTE: I: input, O: output, G: ground, P: power.

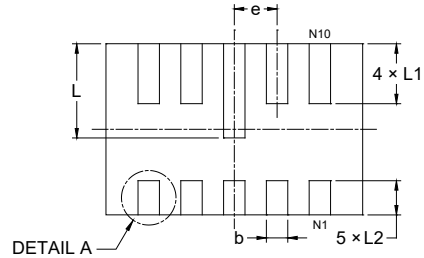
PACKAGE INFORMATION

PACKAGE OUTLINE DIMENSIONS

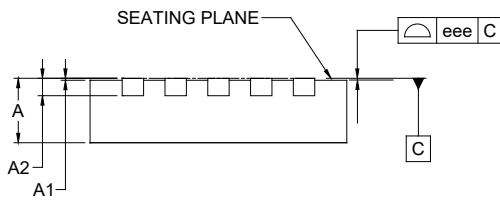
TDFN-3x2-10L



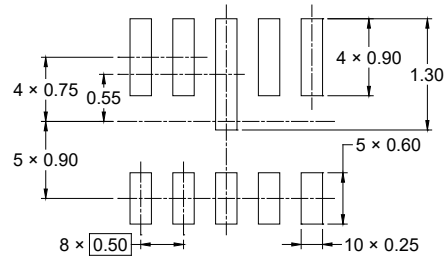
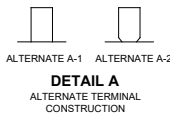
TOP VIEW



BOTTOM VIEW



SIDE VIEW



RECOMMENDED LAND PATTERN (Unit: mm)

Symbol	Dimensions in Millimeters		
	MIN	MOD	MAX
A	0.700	-	0.800
A1	0.000	-	0.050
A2	0.203 REF		
b	0.200	-	0.300
D	2.900	-	3.100
E	1.900	-	2.100
e	0.500 BSC		
L	1.000	-	1.200
L1	0.600	-	0.800
L2	0.300	-	0.500
eee	0.080		

NOTE: This drawing is subject to change without notice.

PACKAGE INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TDFN-3×2-10L	7"	9.5	2.30	3.30	1.10	4.0	4.0	2.0	8.0	Q1

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PACKAGE INFORMATION

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
7" (Option)	368	227	224	8
7"	442	410	224	18

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